



KYOCERA Chemical Corporation
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Molding Compounds for Area Array Packages (BGA, CSP etc.)

Special Epoxy Molding Compounds Optimizing Warpage and Applicable to Fine Pitch Wire for BGA Package

General Properties

Standard Type		KE-1100A-S3	KE-1150	KE-G1200	KE-G1250 LKDS	KE-G1270
Low α Ray Type		KE-2100A-S3	KE-2150	KE-G2200	KE-G2250 LKDS	KE-G2270
Spiral Flow (cm)		190	190	140	180	160
Flow Viscosity (Pa · s)		6	5	9	7	8
Specific Gravity (-)		1.9	2.0	2.0	2.0	2.0
CTE	$\alpha 1$ (x 10 ⁻⁵ /°C)	1.4	1.0	0.8	0.8	1.0
	$\alpha 2$ (x 10 ⁻⁵ /°C)	4.9	4.5	2.7	3.2	4.2
Glass Transition Temp. (°C)		200	185	180	130	180
Flexural Strength (MPa)		130	150	180	180	140
Flexural Modulus (GPa)		15	18	27	25	20

Strong Points

- a) Less Warpage in All Types of Area Array Packages due to High Tg Characteristic.
- b) Applicable to Fine Pitch Wire Bonding with Good Wire Sweep Performance.
- c) Achieve High Yield after Molding due to Excellent Moldability that allows its application to MAP.

Application

- a) Standard P-BGA, HS-BGA and LGA Package.
- b) Multi Chip Module (Stacked or Side by Side Layout)
- c) IC Card, Memory Card etc.

